

### 1.0A SURFACE MOUNT SCHOTTKY BRIDGE

### **Product Summary**

V <sub>RRM</sub> (V)	I <sub>O</sub> (A)	V <sub>F MAX</sub> (V) @ +25°C	I <sub>R MAX</sub> (mA) @ +25°C	
30	1	0.42	1	

### **Features**

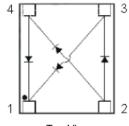
- Low profile package, ideal for thin portable applications
- Low Forward Voltage Drop reduces power dissipation
- Soft switching characteristic ensures that EMI and EFI are minimised.
- Guard Ring Die Construction for transient Protection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

# **Description and Applications**

Packaged in the compact DFN5060-4 the SDM1L30BLP has been designed with low forward voltage and soft switching characteristics to meet the needs of wireless charging applications.

### **Mechanical Data**

- Case: V-DFN5060-4
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
  Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.0715 grams (approximate)



Top View Device Schematic



Top View



Bottom View

### Ordering Information (Note 4)

Part Number	Case	Packaging
SDM1L30BLP-13	V-DFN5060-4	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



SSD3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: W =2012) M = Month (ex: 9 = September)

Date Code Key

Year	201	2	2013		2014	20	15	2016		2017	2	2018
Code	Z		Α		В	(		D		Е		F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	30	<b>V</b>
Average Rectified Output Current	lo	1.0	mA
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (Per Diode)	I <sub>FSM</sub>	50	А

### **Thermal Characteristics**

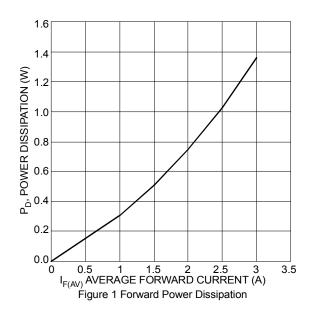
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5)	$R_{ heta JC}$	15	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

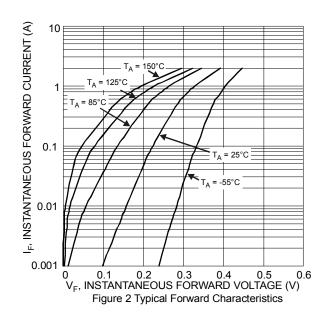
# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop (Per Diode)	V <sub>F</sub>		0.21 0.31	— 0.42	V	I <sub>F</sub> = 0.1A, T <sub>J</sub> = +25°C I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25°C
Leakage Current (Note 6) (Per Diode)	I <sub>R</sub>	_	_	1.0	mA	$V_R = 30V, T_J = +25^{\circ}C$
Total Capacitance	C <sub>T</sub>	_	90	_	pF	$V_R = 30V, f = 1.0MHz,$ $T_J = +25^{\circ}C$

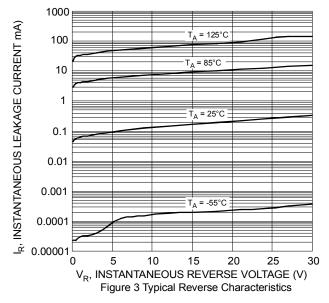
Notes:

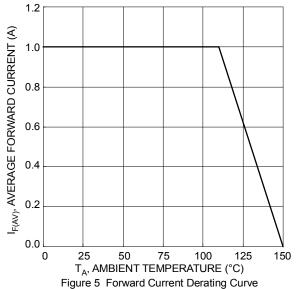
- $5.\ Device\ mounted\ on\ Polymide\ PCB\ with\ 1x\ recommended\ pad\ layout,\ with\ minimum\ recommended\ pad\ layout\ per\ http://www.diodes.com.$
- 6. Short duration pulse test used to minimize self-heating effect.











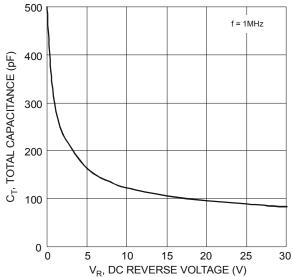
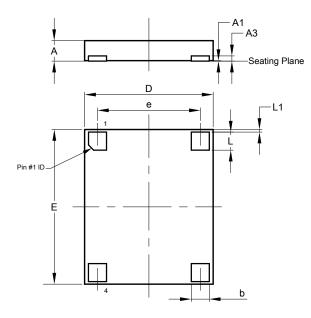


Figure 4 Total Capacitance vs. Reverse Voltage



# **Package Outline Dimensions**

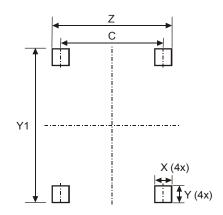
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



V-DFN5060-4							
Dim	Min	Max	Тур				
Α	0.75	0.85	0.80				
A1	0	0.05	0.02				
<b>A</b> 3	1	1	0.203				
b	0.65	0.75	0.70				
D	4.95	5.05	5.00				
е	-	-	4.00				
Е	5.95	6.05	6.00				
١	0.65	0.75	0.70				
L1	0.05	0.15	0.10				
All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	4.00
X	0.75
Y	0.95
Y1	6.20
Z	4.75



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